

Final Product/Process Change Notification Document #: FPCN22699Z Issue Date: 30 July 2019

| Process – Assembly | Change of direct material supplier | |
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| Process – Assembly | Change of lead frame finishing material / area (internal) | |
| Change Category: | Type of Change | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com. | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or < <u>Daniel.vanderstraeten@onsemi.com</u> >. | |
| PPAP Availability Date: | 1 June 2019 | |
| Sample Availability Date: | 1 June 2019 | |
| Samples: | Contact your local ON Semiconductor Sales Office to place sample order or < <u>PCN.samples@onsemi.com</u> > Sample requests are to be submitted no later than 45 days after publication of this change notification. | |
| Contact information: | Contact your local ON Semiconductor Sales Office or < <u>Bernard.blanchet@onsemi.com</u> > | |
| Product Category: | Active components – Integrated circuits | |
| Current Material Last Delivery Date: | 19 April 2020 The Current Material Last Delivery Date may be subject to change based on build and depletion of th current (unchanged) material inventory. | |
| Current Material Last Order Date: | NA NA | |
| Proposed Changed Material First Ship Date: | 30 July 2020 or earlier upon customer approval. | |
| Title of Change: | Improve the quality of SSOP36 package by qualifying a new lead frame without silver (Ag) into plating moving from NiPdAu-Ag to NiPdAu for LED Drivers devices (Front Lighting) assembled in OSPI Carmona (Philippines) and Amkor (ATP1) Philippines. | |

Description and Purpose:

| | Before Change Description | After Change Description |
|---------------------|---------------------------|--------------------------|
| LeadFrame plating | NiPdAu-Ag | NiPdAu |
| Lead Frame Supplier | HDS | ASM |

There is no product marking change as a result of this change.

| Reason / Motivation for Change: | Change benefits for customer: Eliminate the risk of leads discoloration (no wetting) under a certain environment. Risk for late release for customer: yield loss in their PCB assembly lines Quality improvement: Yes | | |
|---|---|--|--|
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts. | | |
| Sites Affected: | ON Semiconductor Sites: ON Carmona, Philippines | External Foundry/Subcon Sites: Amkor Phil 1 | |

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Marking of Parts/ Traceability of Change:

New part number and date code. .

Reliability Data Summary:

ON CARMONA PHILIPPINES (OSPI)

QV: 0L763-001 / 0L763-011

RMS: 054851 Package: SSOP36-EP

| Test | Specification Condition | | Interval | Results |
|-------|-------------------------|--|------------|---------|
| PC | JESD22 A113 J-STD-020 | Preconditioning: (Test@Rm) SMD only; Moist. Precond. MSL=3 @260°C | | 0/480 |
| UHAST | JESD22 A118 | Unbiased Highly Accelerated Stress Test: (Test @R) 110°C/85% RH, ~ 18.8 psig, no bias for 264hrs. | | 0/480 |
| PC-TC | JESD22 A104 | Temp Cycle: (Test @H) -55°C to+165°C. | 500 cycles | 0/480 |
| HTSL | JESD22 A103 | High Temp Storage Life (Test @R/H) TA= 150°C | 1008 hrs | 0/480 |
| HTOL | JESD22 A108 | High Temp Op Life: (Test @ R/H/C) TA=125°C | 1008 hrs. | 0/160 |
| WBP | Mil-Std-883 Meth 2011 | Wire Bond Pull: Cpk>1.67 | | >1.67 |
| SD | J-STD-002or JESD22 B102 | Solderability TA=245°C | | 0/30 |
| PD | JESD22 B100 | POD Cpk>1.67 | | 0/40 |

Amkor PHILIPPINES (ATP1)

QV: 0L763-013 / 0L763-001 RMS: 039592 / 033601 Package: SSOP36-EP

| Test | Specification | Condition | Interval | Results |
|-------|-------------------------|--|------------------|---------|
| PC | JESD22 A113 J-STD-020 | Preconditioning: (Test@Rm) SMD only; Moist. Precond. | | 0/508 |
| | | MSL=3 @260°C | | |
| UHAST | JESD22 A118 | Unbiased Highly Accelerated Stress Test: (Test @R) | | 0/160 |
| | | 110°C/85% RH, ~ 18.8 psig, no bias for 264hrs. | | |
| HAST | JESD A110B | Biased-HAST, 110°C/85%RH | 264 hrs | 0/160 |
| PC-TC | JESD22 A104 | Temp Cycle: (Test @H) -65°C to+150°C. | 500 cycles | 0/160 |
| PTC | JESD22-A 105 | -40°C/125°C | 1000cycles | 0/24 |
| HTSL | JESD22 A103 | High Temp Storage Life (Test @R/H) TA= 150°C | 504 hrs 1008 hrs | 0/80 |
| HTOL | JESD22 A108 | High Temp Op Life: (Test @ R/H/C) TA=125°C | 1000 hrs. | 0/126 |
| WBP | Mil-Std-883 Meth 2011 | Wire Bond Pull: Cpk>1.67 | | 0/10 |
| SD | J-STD-002or JESD22 B122 | Solderability TA=245°C | | 0/30 |
| PD | JESD22 B100 | POD Cpk>1.67 | | 0/30 |

NOTE: AEC-1pager is attached.

To view attachments:

- $1. \quad \textit{Download pdf copy of the PCN to your computer} \\$
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file/s

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| Electrical Characteristic Summary |
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Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|--|
| NCV78763DQ0AR2G | NCV78763DQ0CR2G | OSPI: 0L763-001/0L763-011 ATP1: 0L763-001/0L763-013 |
| NCV78763DQ6AR2G | NCV78763DQ6CR2G | OSPI: 0L763-001/0L763-011 ATP1: 0L763-001/0L763-013 |
| NCV78663DQ0R2G | NCV78663DQ0CR2G | OSPI: 0L763-001/0L763-011 |

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Appendix A: Changed Products

| Product | Customer Part Number | New Part Number | Qualification Vehicle |
|-----------------|----------------------|-----------------|-------------------------------|
| NCV78663DQ0R2G | | NCV78663DQ0CR2G | 0L763-001 0L763-011 |
| NCV78763DQ0AR2G | | NCV78763DQ0CR2G | 0L763-001 0L763-011 0L763-013 |
| NCV78763DQ6AR2G | | NCV78763DQ6CR2G | 0L763-001 0L763-011 0L763-013 |